Dual supply translating transceiver; open drain; auto direction sensing Rev. 4 — 30 June 2021 Pro-

Product data sheet

### 1. General description

The NXS0104 is a 4-bit, dual supply translating transceiver with auto direction sensing, that enables bidirectional voltage level translation. It features two 4-bit input-output ports (An and Bn), one output enable input (OE) and two supply pins ( $V_{CC(A)}$  and  $V_{CC(B)}$ ).  $V_{CC(A)}$  can be supplied at any voltage between 1.65 V and 3.6 V and  $V_{CC(B)}$  can be supplied at any voltage between 2.3 V and 5.5 V, making the device suitable for translating between any of the voltage nodes (1.8 V, 2.5 V, 3.3 V and 5.0 V). Pins An and OE are referenced to  $V_{CC(A)}$  and pins Bn are referenced to  $V_{CC(B)}$ . A LOW level at pin OE causes the outputs to assume a high-impedance OFF-state. This device is fully specified for partial power-down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

### 2. Features and benefits

- Wide supply voltage range:
  - $V_{CC(A)}$ : 1.65 V to 3.6 V and  $V_{CC(B)}$ : 2.3 V to 5.5 V
- Maximum data rates:
  - Push-pull: 24 Mbps
- I<sub>OFF</sub> circuitry provides partial Power-down mode operation
- Inputs accept voltages up to 5.5 V
- ESD protection:
  - HBM: ANSI/ESDA/Jedec JS-001 Class 2 exceeds 2.5 kV for A port
  - HBM: ANSI/ESDA/Jedec JS-001 Class 3B exceeds 15 kV for B port
  - CDM: ANSI/ESDA/Jedec JS-002 Class C3 exceeds 1.5 kV
  - IEC61000-4-2 contact discharge exceeds 8000 V for B port
- Latch-up performance exceeds 100 mA per JESD 78B Class II
- Multiple package options
- Specified from -40 °C to +85 °C and -40 °C to +125 °C

### 3. Applications

- Desktop PC
- Handset
- Smartphone
- Tablet

## 4. Ordering information

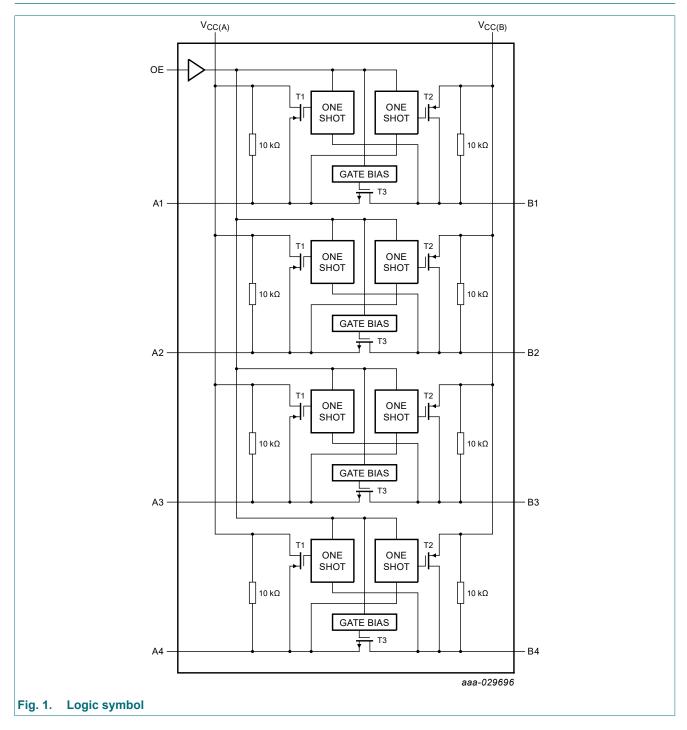
### Table 1. Ordering information

Type number	Package							
	Temperature range	Name	Description	Version				
NXS0104PW	-40 °C to +125 °C	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1				
NXS0104BQ	-40 °C to +125 °C	DHVQFN14	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 × 3 × 0.85 mm	SOT762-1				
NXS0104GU12	-40 °C to +125 °C	XQFN12	plastic, extremely thin quad flat package; no leads; 12 terminals; body 1.70 × 2.0 × 0.50 mm	SOT1174-1				
NXS0104UM	-40 °C to +125 °C	WLCSP12	wafer level chip-scale package; 12 bumps; 1.36 × 1.86 × 0.60 mm	SOT8019-1				

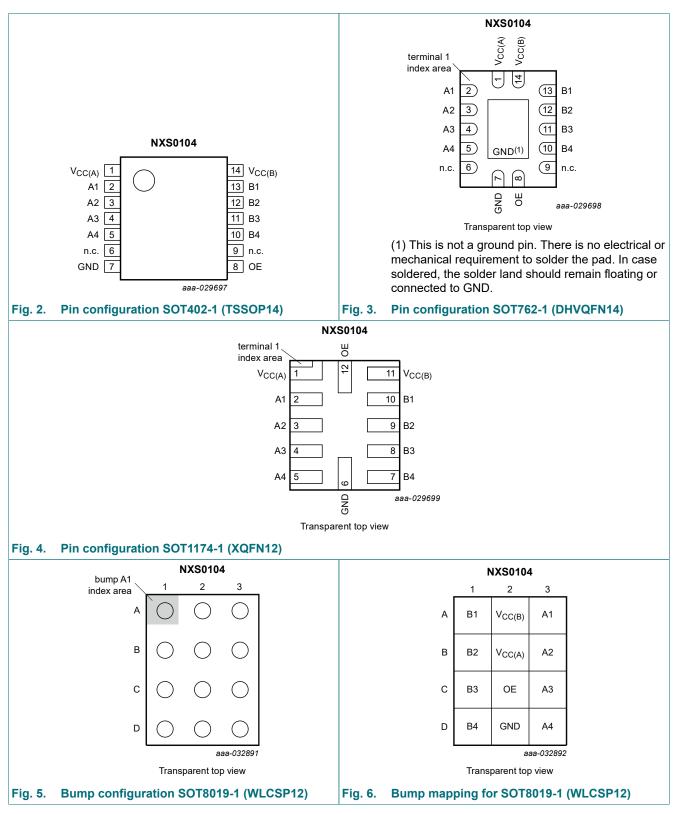
## 5. Marking

Table 2. Marking				
Type number	Marking code			
NXS0104PW	NXS0104			
NXS0104BQ	S0104			
NXS0104GU12	m4			
NXS0104UM	m4			

## 6. Functional diagram



### 7. Pinning information



### 7.1. Pinning

Table 3. Pin desc	cription		
Symbol	Pin		Description
	SOT402-1, SOT762-1	SOT1174-1	
V <sub>CC(A)</sub>	1	1	supply voltage A
A1, A2, A3, A4	2, 3, 4, 5	2, 3, 4, 5	data input or output (referenced to V <sub>CC(A)</sub> )
n.c.	6, 9	-	not connected
GND	7	6	ground (0 V)
OE	8	12	output enable input (active HIGH; referenced to $V_{CC(A)}$ )
B4, B3, B2, B1	10, 11, 12, 13	7, 8, 9, 10	data input or output (referenced to V <sub>CC(B)</sub> )
V <sub>CC(B)</sub>	14	11	supply voltage B

### 7.2. Pin description

#### Table 4. Bump description for SOT8019-1 (WLCSP12)

Symbol	Bump	Description
V <sub>CC(A)</sub>	B2	supply voltage A
A1, A2, A3, A4	A3, B3, C3, D3	data input or output (referenced to $V_{CC(A)}$ )
GND	D2	ground (0 V)
OE	C2	output enable input (active HIGH; referenced to V <sub>CC(A)</sub> )
B1, B2, B3, B4	A1, B1, C1, D1	data input or output (referenced to $V_{CC(B)}$ )
V <sub>CC(B)</sub>	A2	supply voltage B

## 8. Functional description

#### Table 5. Function table

H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

Supply voltage		Input	Input/output	
V <sub>CC(A)</sub> [1]	V <sub>CC(B)</sub>	OE	An	Bn
1.65 V to 3.6 V	2.3 V to 5.5 V	L	Z	Z
1.65 V to 3.6 V	2.3 V to 5.5 V	Н	input or output	output or input
GND[2]	GND[2]	Х	Z	Z

### 9. Limiting values

#### Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>CC(A)</sub>	supply voltage A			-0.5	+6.5	V
V <sub>CC(B)</sub>	supply voltage B			-0.5	+6.5	V
VI	input voltage	A port and OE input	[1]	-0.5	+6.5	V
		B port	[1]	-0.5	+6.5	V
Vo	output voltage	Active mode	[1] [2]			
		A or B port		-0.5	V <sub>CCO</sub> + 0.5	V
		Power-down or 3-state mode	[1]			
		A port		-0.5	+4.6	V
		B port		-0.5	+6.5	V
I <sub>IK</sub>	input clamping current	V <sub>1</sub> < 0 V		-50	-	mA
Ι <sub>ΟΚ</sub>	output clamping current	V <sub>O</sub> < 0 V		-50	-	mA
lo	output current	$V_{O} = 0 V$ to $V_{CCO}$	[2]	-	±50	mA
I <sub>CC</sub>	supply current	I <sub>CC(A)</sub> or I <sub>CC(B)</sub>		-	100	mA
I <sub>GND</sub>	ground current			-100	-	mA
T <sub>stg</sub>	storage temperature			-65	+150	°C
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = -40 °C to +125 °C				
		SOT402-1 (TSSOP14) SOT762-1 (DHVQFN14)	[3]	-	500	mW
		SOT1174-1 (XQFN12) SOT8019-1 (WLCSP12)	[4]	-	250	mW

[1] The minimum input and minimum output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] V<sub>CCO</sub> is the supply voltage associated with the output.

[3] For SOT402-1 (TSSOP14) package: P<sub>tot</sub> derates linearly with 7.3 mW/K above 81 °C.

For SOT762-1 (DHVQFN14) package: Ptot derates linearly with 9.6 mW/K above 98 °C.

[4] For SOT8019-1 (WLCSP12) package: Ptot derates linearly with 7.3 mW/K above 116 °C.

## 10. Recommended operating conditions

#### Table 7. Recommended operating conditions [1] [2]

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC(A)</sub>	supply voltage A		1.65	3.6	V
V <sub>CC(B)</sub>	supply voltage B		2.3	5.5	V
T <sub>amb</sub>	ambient temperature		-40	+125	°C
Δt/ΔV	input transition rise and fall rate	A or B port; push-pull driving			
		$V_{CC(A)}$ = 1.65 V to 3.6 V; $V_{CC(B)}$ = 2.3 V to 5.5 V	-	10	ns/V
		OE input			
		$V_{CC(A)} = 1.65 \text{ V to } 3.6 \text{ V};$ $V_{CC(B)} = 2.3 \text{ V to } 5.5 \text{ V}$	-	10	ns/V

[1] The A and B sides of an unused I/O pair must be held in the same state, both at V<sub>CCI</sub> or both at GND.

[2]  $V_{CC(A)}$  must be less than or equal to  $V_{CC(B)}$  and  $V_{CC(A)}$  must not exceed 3.6 V.

### **11. Static characteristics**

#### Table 8. Typical static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V); T<sub>amb</sub> = 25 °C.[1]

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I <sub>I</sub>	input leakage current	OE input; $V_{CC(A)}$ = 1.65 V to 3.6 V; $V_{CC(B)}$ = 2.3 V to 5.5 V	-	-	±1	μA
I <sub>OZ</sub>	OFF-state output current	A or B port; OE = 0 V; V <sub>CC(A)</sub> = 1.65 V to 3.6 V; V <sub>CC(B)</sub> = 2.3 V to 5.5 V	-	-	±1	μA
I <sub>OFF</sub> power-off leakage	A port; $V_{CC(A)} = 0 V$ ; $V_{CC(B)} = 0 V$ to 5.5 V	-	-	±1	μA	
	current	B port; $V_{CC(B)} = 0 V$ ; $V_{CC(A)} = 0 V$ to 3.6 V	-	-	±1	μA
CI	input capacitance	OE input; V <sub>CC(A)</sub> = 3.3 V; V <sub>CC(B)</sub> = 3.3 V	-	2	-	pF
C <sub>I/O</sub>	input/output	A port; V <sub>CC(A)</sub> = 3.3 V; V <sub>CC(B)</sub> = 3.3 V				
	capacitance	enabled	-	10	-	pF
		disabled	-	4	-	pF
		B port; V <sub>CC(A)</sub> = 3.3 V; V <sub>CC(B)</sub> = 3.3 V				
		enabled	-	10	-	pF
		disabled	-	7	-	pF

[1]  $V_{CC(A)}$  must be less than or equal to  $V_{CC(B)}$  and  $V_{CC(A)}$  must not exceed 3.6 V.

#### Table 9. Typical supply current

At recommended operating conditions; voltages are referenced to GND (ground = 0 V); T<sub>amb</sub> = 25 °C.

V <sub>CC(A)</sub>	V <sub>CC(B)</sub>	V <sub>CC(B)</sub>						
	2.5 V	2.5 V		3.3 V		5.0 V		
	I <sub>CC(A)</sub>	I <sub>CC(B)</sub>	I <sub>CC(A)</sub>	I <sub>CC(B)</sub>	I <sub>CC(A)</sub>	I <sub>CC(B)</sub>		
1.8 V	0.1	0.5	0.1	1.5	0.1	4.6	μA	
2.5 V	0.1	0.1	0.1	0.8	0.1	3.8	μA	
3.3 V	-	-	0.1	0.1	0.1	2.8	μΑ	

#### Table 10. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).[1]

Symbol	Parameter	Conditions	-40 °C to	-40 °C to +85 °C		-40 °C to +125 °C	
			Min	Max	Min	Мах	
VIH	HIGH-level input	A port					
voltage	voltage	$V_{CC(A)} = 1.65 V \text{ to } 1.95 V;$ $V_{CC(B)} = 2.3 V \text{ to } 5.5 V$	V <sub>CC(A)</sub> - 0.2	V <sub>CC(A)</sub>	V <sub>CC(A)</sub> - 0.2	V <sub>CC(A)</sub>	V
		$V_{CC(A)} = 2.3 V \text{ to } 3.6 V;$ $V_{CC(B)} = 2.3 V \text{ to } 5.5 V$	V <sub>CC(A)</sub> - 0.4	V <sub>CC(A)</sub>	V <sub>CC(A)</sub> - 0.4	V <sub>CC(A)</sub>	V
		B port					
		$V_{CC(A)}$ = 1.65 V to 3.6 V; $V_{CC(B)}$ = 2.3 V to 5.5 V	V <sub>CC(B)</sub> - 0.4	V <sub>CC(B)</sub>	V <sub>CC(B)</sub> - 0.4	V <sub>CC(B)</sub>	V
		OE input					
		$V_{CC(A)}$ = 1.65 V to 3.6 V; $V_{CC(B)}$ = 2.3 V to 5.5 V	0.65V <sub>CC(A)</sub>	V <sub>CC(A)</sub>	0.65V <sub>CC(A)</sub>	V <sub>CC(A)</sub>	V

-	Parameter	Conditions	-40 °C t	o +85 °C	-40 °C to	Unit	
			Min	Max	Min	Max	
V <sub>IL</sub>	LOW-level input	A or B port					
	voltage	$V_{CC(A)} = 1.65 \text{ V to } 3.6 \text{ V};$ $V_{CC(B)} = 2.3 \text{ V to } 5.5 \text{ V}$	0	0.15	0	0.15	V
		OE input					
		$V_{CC(A)} = 1.65 \text{ V to } 3.6 \text{ V};$ $V_{CC(B)} = 2.3 \text{ V to } 5.5 \text{ V}$	0	0.35V <sub>CC(A)</sub>	0	0.35V <sub>CC(A)</sub>	V
V <sub>OH</sub>	HIGH-level	A port; $I_O = -20 \ \mu A$ ; $V_I \ge V_{CC(B)} - 0.4 \ V$					
	output voltage	$V_{CC(A)} = 1.65 \text{ V to } 3.6 \text{ V};$ $V_{CC(B)} = 2.3 \text{ V to } 5.5 \text{ V}$	0.67V <sub>CC(A)</sub>	-	0.67V <sub>CC(A)</sub>	-	V
		B port; $I_O = -20 \ \mu A$ ; $V_I \ge V_{CC(A)} - 0.2 \ V$					
		$V_{CC(A)} = 1.65$ V to 3.6 V; $V_{CC(B)} = 2.3$ V to 5.5 V	0.67V <sub>CC(B)</sub>	-	0.67V <sub>CC(B)</sub>	-	V
V <sub>OL</sub>	LOW-level	A or B port; $I_0 = 1 \text{ mA}$ ; $V_1 \le 0.15 \text{ V}$				0.15 0.35V <sub>CC(A)</sub>	
	output voltage	$V_{CC(A)} = 1.65$ V to 3.6 V; $V_{CC(B)} = 2.3$ V to 5.5 V	-	0.4	-	0.4	V
l <sub>l</sub>	input leakage current	OE input; $V_{CC(A)} = 1.65$ V to 3.6 V; $V_{CC(B)} = 2.3$ V to 5.5 V	-	±2	-	±12	μA
I <sub>OZ</sub>	OFF-state output current	A or B port; $V_{CC(A)}$ = 1.65 V to 3.6 V; $V_{CC(B)}$ = 2.3 V to 5.5 V	-	±2	-	±12	μA
I <sub>OFF</sub>	power-off leakage current	A port; $V_{CC(A)} = 0 V$ ; $V_{CC(B)} = 0 V$ to 5.5 V	-	±2	-	±12	μA
		B port; $V_{CC(B)} = 0 V$ ; $V_{CC(A)} = 0 V$ to 3.6 V	-	±2	-	±12	μA
I <sub>CC</sub>	supply current	$OE = 0 V \text{ or } V_{CC(A)}$ ; An, Bn open					
		I <sub>CC(A)</sub>					
		$V_{CC(A)} = 1.65$ V to 3.6 V; $V_{CC(B)} = 2.3$ V to 5.5 V	-	2.4	-	15	μA
		V <sub>CC(A)</sub> = 3.6 V; V <sub>CC(B)</sub> = 0 V	-	2.2	-	15	μA
		V <sub>CC(A)</sub> = 0 V; V <sub>CC(B)</sub> = 5.5 V	-	-1	-	-8	μA
		I <sub>CC(B)</sub>					
		$V_{CC(A)} = 1.65 \text{ V to } 3.6 \text{ V};$ $V_{CC(B)} = 2.3 \text{ V to } 5.5 \text{ V}$	-	12	-	30	μA
		V <sub>CC(A)</sub> = 3.6 V; V <sub>CC(B)</sub> = 0 V	-	-1	-	-5	μA
		V <sub>CC(A)</sub> = 0 V; V <sub>CC(B)</sub> = 5.5 V	-	1	-	6	μA
		$I_{CC(A)} + I_{CC(B)}$					
		V <sub>CC(A)</sub> = 1.65 V to 3.6 V; V <sub>CC(B)</sub> = 2.3 V to 5.5 V	-	14.4	-	45	μA

[1]  $V_{CC(A)}$  must be less than or equal to  $V_{CC(B)}$  and  $V_{CC(A)}$  must not exceed 3.6 V.

## **12. Dynamic characteristics**

#### Table 11. Dynamic characteristics for temperature range -40 °C to +85 °C

Voltages are referenced to GND (ground = 0 V); for test circuit see Fig. 10; for waveforms see Fig. 7 to Fig. 9.

Symbol	Parameter	Conditions			Vc	C(B)			Unit
			2.5 V ± 0.2 V		3.3 V ± 0.3 V		5.0 V ± 0.5 V		
			Min	Max	Min	Max	Min	Max	1
V <sub>CC(A)</sub> =	1.8 V ± 0.15 V	-	1						
t <sub>PHL</sub>	HIGH to LOW propagation delay	A to B	-	4.6	-	4.7	-	5.8	ns
t <sub>PLH</sub>	LOW to HIGH propagation delay	A to B	-	7.1	-	6.8	-	7.0	ns
t <sub>PHL</sub>	HIGH to LOW propagation delay	B to A	-	4.4	-	4.5	-	4.7	ns
t <sub>PLH</sub>	LOW to HIGH propagation delay	B to A	-	5.3	-	4.5	-	0.5	ns
t <sub>en</sub>	enable time	OE to A, B [1]	-	200	-	200	-	200	ns
t <sub>dis</sub>	disable time	OE to A, B; no external load [1] [2]	-	35	-	35	-	35	ns
		OE to A	-	140	-	140	-	145	ns
		OE to B	-	125	-	175	-	125	ns
t <sub>TLH</sub>	LOW to HIGH	A port	3.2	9.5	2.3	9.3	1.8	7.6	ns
	output transition time	B port	3.3	10.8	2.7	9.1	2.7	7.6	ns
t <sub>THL</sub>	HIGH to LOW	A port	2.0	5.9	1.9	6.0	1.7	13.3	ns
output time	output transition time	B port	2.9	7.6	2.8	7.5	2.8	10.0	ns
t <sub>sk(o)</sub>	output skew time	between channels [3]	-	0.7	-	0.7	-	0.7	ns
t <sub>W</sub>	pulse width	data inputs	41	-	41	-	41	-	ns
f <sub>data</sub>	data rate		-	24	-	24	-	24	Mbps

### Dual supply translating transceiver; open drain; auto direction sensing

Symbol	Parameter	Conditions		V <sub>CC(B)</sub>						
			2.5 V	2.5 V ± 0.2 V		3.3 V ± 0.3 V		± 0.5 V		
			Min	Max	Min	Max	Min	Max		
V <sub>CC(A)</sub> =	2.5 V ± 0.2 V									
t <sub>PHL</sub>	HIGH to LOW propagation delay	A to B	-	3.2	-	3.3	-	3.4	ns	
t <sub>PLH</sub>	LOW to HIGH propagation delay	A to B	-	3.5	-	4.4	-	4.6	ns	
t <sub>PHL</sub>	HIGH to LOW propagation delay	B to A	-	3.0	-	3.6	-	4.3	ns	
t <sub>PLH</sub>	LOW to HIGH propagation delay	B to A	-	2.5	-	1.6	-	0.7	ns	
t <sub>en</sub>	enable time	OE to A, B [1]	-	200	-	200	-	200	ns	
t <sub>dis</sub>	disable time	OE to A, B; no external load [1] [2]	-	35	-	35	-	35	ns	
		OE to A	-	105	-	105	-	105	ns	
		OE to B	-	125	-	175	-	120	ns	
t <sub>TLH</sub>	LOW to HIGH	A port	2.8	7.5	2.6	6.6	1.8	6.5	ns	
	output transition time	B port	3.2	8.5	2.9	7.3	2.4	6.3	ns	
t <sub>THL</sub>	HIGH to LOW	A port	1.9	5.7	1.9	5.5	1.8	5.3	ns	
	output transition time	B port	2.2	7.8	2.4	6.7	2.6	6.6	ns	
t <sub>sk(o)</sub>	output skew time	between channels [3]	-	0.7	-	0.7	-	0.7	ns	
t <sub>W</sub>	pulse width	data inputs	41	-	41	-	41	-	ns	
f <sub>data</sub>	data rate		-	24	-	24	-	24	Mbps	
V <sub>CC(A)</sub> =	3.3 V ± 0.3 V									
t <sub>PHL</sub>	HIGH to LOW propagation delay	A to B	-	-	-	2.4	-	3.1	ns	
t <sub>PLH</sub>	LOW to HIGH propagation delay	A to B	-	-	-	4.2	-	4.4	ns	
t <sub>PHL</sub>	HIGH to LOW propagation delay	B to A	-	-	-	2.5	-	3.3	ns	
t <sub>PLH</sub>	LOW to HIGH propagation delay	B to A	-	-	-	2.5	-	2.6	ns	
t <sub>en</sub>	enable time	OE to A, B [1]	-	-	-	200	-	200	ns	
t <sub>dis</sub>	disable time	OE to A, B; no external load [1] [2]	-	-	-	35	-	35	ns	
		OE to A	-	-	-	150	-	150	ns	
		OE to B	-	-	-	170	-	120	ns	
t <sub>TLH</sub>	LOW to HIGH	A port	-	-	2.3	6.2	1.9	6.3	ns	
	output transition time	B port	-	-	2.5	6.9	2.1	7.4	ns	
t <sub>THL</sub>	HIGH to LOW	A port	-	-	2.0	5.4	1.9	5.0	ns	
	output transition time		-	-	2.3	7.4	2.4	7.6	ns	
t <sub>sk(o)</sub>	output skew time	between channels [3]	-	-	-	0.7	-	0.7	ns	
t <sub>W</sub>	pulse width	data inputs	-	-	41	-	41	-	ns	
f <sub>data</sub>	data rate		-	-	-	24	-	24	Mbps	

[1]

 $t_{en}$  is the same as  $t_{PZL}$  and  $t_{PZH}$ ;  $t_{dis}$  is the same as  $t_{PLZ}$  and  $t_{PHZ}$ . These values are guaranteed by design. Skew between any two outputs of the same package switching in the same direction. [2] [3]

### Table 12. Dynamic characteristics for temperature range -40 °C to +125 °C

Voltages are referenced to GND (ground = 0 V); for test circuit see Fig. 10; for waveforms see Fig. 7 to Fig. 9.

Symbol	Parameter	Conditions			Vc	C(B)			Unit
			2.5 V ± 0.2 V		3.3 V ± 0.3 V		5.0 V :	± 0.5 V	
			Min	Max	Min	Max	Min	Max	
V <sub>CC(A)</sub> =	1.8 V ± 0.15 V								
t <sub>PHL</sub>	HIGH to LOW propagation delay	A to B	-	5.8	-	5.9	-	7.3	ns
t <sub>PLH</sub>	LOW to HIGH propagation delay	A to B	-	8.5	-	8.5	-	8.8	ns
t <sub>PHL</sub>	HIGH to LOW propagation delay	B to A	-	5.5	-	5.7	-	5.9	ns
t <sub>PLH</sub>	LOW to HIGH propagation delay	B to A	-	6.7	-	5.7	-	0.7	ns
t <sub>en</sub>	enable time	OE to A, B [1]	-	200	-	200	-	200	ns
t <sub>dis</sub>	disable time	OE to A, B; no external load [1] [2]	-	45	-	45	-	45	ns
		OE to A	-	140	-	140	-	145	ns
		OE to B	-	125	-	175	-	125	ns
t <sub>TLH</sub>	LOW to HIGH	A port	3.2	11.9	2.3	11.7	1.8	9.5	ns
	output transition time	B port	3.3	13.5	2.7	11.4	2.7	9.5	ns
t <sub>THL</sub>	HIGH to LOW	A port	2.0	7.4	1.9	7.5	1.7	16.7	ns
	output transition time	B port	2.9	9.5	2.8	9.4	2.8	12.5	ns
t <sub>sk(o)</sub>	output skew time	between channels [3]	-	0.8	-	0.8	-	0.8	ns
t <sub>W</sub>	pulse width	data inputs	50	-	41	-	41	-	ns
f <sub>data</sub>	data rate		-	20	-	24	-	24	Mbps
V <sub>CC(A)</sub> =	2.5 V ± 0.2 V								
t <sub>PHL</sub>	HIGH to LOW propagation delay	A to B	-	4.0	-	4.2	-	4.3	ns
t <sub>PLH</sub>	LOW to HIGH propagation delay	A to B	-	4.4	-	5.2	-	5.5	ns
t <sub>PHL</sub>	HIGH to LOW propagation delay	B to A	-	3.8	-	4.5	-	5.4	ns
t <sub>PLH</sub>	LOW to HIGH propagation delay	B to A	-	3.2	-	2.0	-	0.9	ns
t <sub>en</sub>	enable time	OE to A, B [1]	-	200	-	200	-	200	ns
t <sub>dis</sub>	disable time	OE to A, B; no external load [1] [2]	-	45	-	45	-	45	ns
		OE to A	-	105	-	105	-	105	ns
		OE to B	-	125	-	175	-	120	ns
t <sub>TLH</sub>	LOW to HIGH	A port	2.8	9.3	2.6	8.3	1.8	7.8	ns
	output transition time	B port	3.2	10.4	2.9	9.7	2.4	8.3	ns
t <sub>THL</sub>	HIGH to LOW	A port	1.9	7.2	1.9	6.9	1.8	6.7	ns
	output transition time	B port	2.2	9.8	2.4	8.4	2.6	8.3	ns
t <sub>sk(o)</sub>	output skew time	between channels [3]	-	0.8	-	0.8	-	0.8	ns
t <sub>W</sub>	pulse width	data inputs	50	-	41	-	41	-	ns
f <sub>data</sub>	data rate		-	20	-	24	-	24	Mbps

Dual supply translating	j transceiver; o	pen drain; auto	direction sensing
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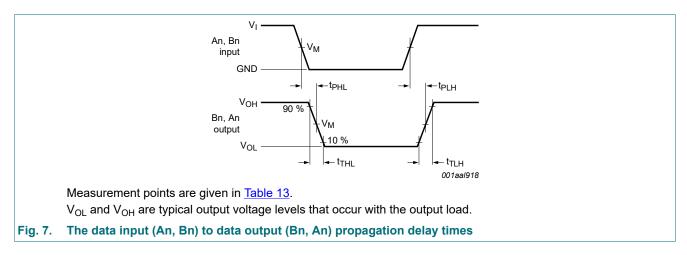
		Conditions	Conditions			V <sub>CC(B)</sub>						
			2.5 V ± 0.2 V		3.3 V ± 0.3 V		5.0 V ± 0.5 V					
				Min	Max	Min	Max	Min	Max			
V <sub>CC(A)</sub>	= 3.3 V ± 0.3 V											
t <sub>PHL</sub>	HIGH to LOW propagation delay	A to B		-	-	-	3.0	-	3.9	ns		
t <sub>PLH</sub>	LOW to HIGH propagation delay	A to B		-	-	-	5.3	-	5.5	ns		
t <sub>PHL</sub>	HIGH to LOW propagation delay	B to A		-	-	-	3.2	-	4.2	ns		
t <sub>PLH</sub>	LOW to HIGH propagation delay	B to A		-	-	-	3.2	-	3.3	ns		
t <sub>en</sub>	enable time	OE to A, B	[1]	-	-	-	200	-	200	ns		
t <sub>dis</sub>	disable time	OE to A, B; no external load	[1] [2]	-	-	-	45	-	45	ns		
		OE to A		-	-	-	150	-	150	ns		
		OE to B		-	-	-	170	-	120	ns		
t <sub>TLH</sub>	LOW to HIGH	A port		-	-	2.3	7.0	1.9	7.4	ns		
	output transition time	B port		-	-	2.5	8.0	2.1	9.3	ns		
t <sub>THL</sub>	HIGH to LOW	A port		-	-	2.0	6.8	1.9	6.3	ns		
output transiti time	output transition time	B port		-	-	2.3	9.3	2.4	9.5	ns		
t <sub>sk(o)</sub>	output skew time	between channels	[3]	-	-	-	0.8	-	0.8	ns		
t <sub>W</sub>	pulse width	data inputs		-	-	41	-	41	-	ns		
f <sub>data</sub>	data rate			-	-	-	24	-	24	Mbps		

[1]  $t_{en}$  is the same as  $t_{PZL}$  and  $t_{PZH}$ ;  $t_{dis}$  is the same as  $t_{PLZ}$  and  $t_{PHZ}$ .

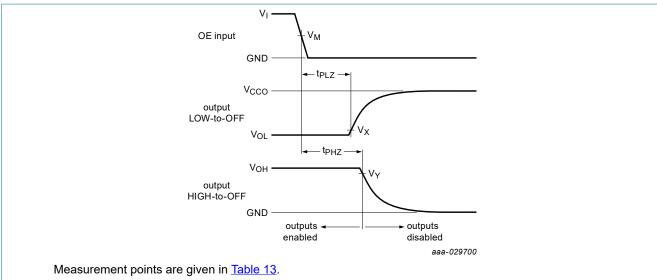
These values are guaranteed by design. [2] [3]

Skew between any two outputs of the same package switching in the same direction.

### 12.1. Waveforms and test circuit

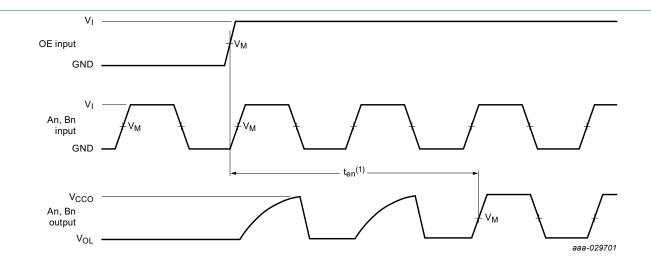


#### Dual supply translating transceiver; open drain; auto direction sensing



 $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.  $V_{CCO}$  is the supply voltage associated with the output.

#### Fig. 8. Disable times



(1) The enable time ( $t_{en}$ ) indicates the amount of time the user must allow for one one-shot circuitry to become operational after OE is taken HIGH. See also <u>Section 13.6</u>

Measurement points are given in <u>Table 13</u>.

V<sub>OL</sub> is a typical output voltage level that occur with the output load.

 $V_{\text{CCO}}$  is the supply voltage associated with the output.

#### Fig. 9. Enable times

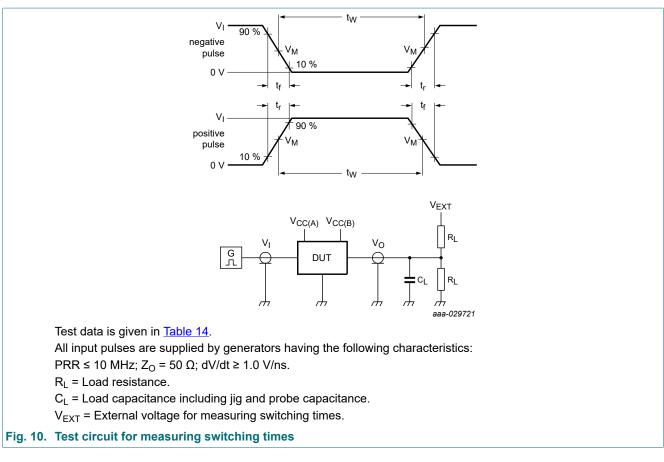
#### Table 13. Measurement points

Supply voltage	Input	Output	Output					
V <sub>cco</sub>	V <sub>M</sub> [1]	V <sub>M</sub> [2]	V <sub>X</sub>	V <sub>Y</sub>				
1.8 V ± 0.15 V	0.5V <sub>CCI</sub>	0.5V <sub>CCO</sub>	V <sub>OL</sub> + 0.15 V	V <sub>OH</sub> - 0.15 V				
2.5 V ± 0.2 V	0.5V <sub>CCI</sub>	0.5V <sub>CCO</sub>	V <sub>OL</sub> + 0.15 V	V <sub>OH</sub> - 0.15 V				
3.3 V ± 0.3 V	0.5V <sub>CCI</sub>	0.5V <sub>CCO</sub>	V <sub>OL</sub> + 0.3 V	V <sub>OH</sub> - 0.3 V				
5.0 V ± 0.5 V	0.5V <sub>CCI</sub>	0.5V <sub>CCO</sub>	V <sub>OL</sub> + 0.3 V	V <sub>OH</sub> - 0.3 V				

[1]  $V_{CCI}$  is the supply voltage associated with the input.

[2]  $V_{CCO}$  is the supply voltage associated with the output.

#### Dual supply translating transceiver; open drain; auto direction sensing



### Table 14. Test data

Supply voltage		Input		Load	_oad		V <sub>EXT</sub>		
V <sub>CC(A)</sub>	V <sub>CC(B)</sub>	V <sub>I</sub> [1]	Δt/ΔV	CL	R <sub>L</sub> [2]	t <sub>PLH</sub> , t <sub>PHL</sub>	t <sub>PZH</sub> , t <sub>PHZ</sub>	t <sub>PZL</sub> , t <sub>PLZ</sub> [3]	
1.65 V to 3.6 V	2.3 V to 5.5 V	V <sub>CCI</sub>	≤ 1.0 ns/V	15 pF	50 kΩ, 1 MΩ	open	open	2V <sub>CCO</sub>	

[1] V<sub>CCI</sub> is the supply voltage associated with the input.

[2] For measuring data rate, pulse width, propagation delay and output rise and fall measurements,  $R_L = 1 M\Omega$ .

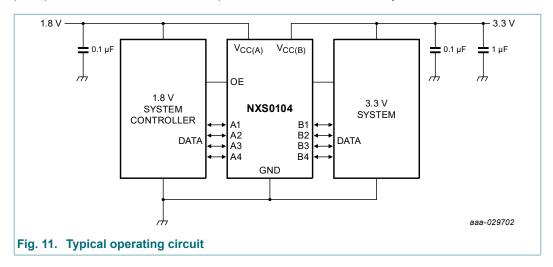
For measuring enable and disable times,  $R_L = 50 \text{ k}\Omega$ .

[3]  $V_{CCO}$  is the supply voltage associated with the output.

### **13. Application information**

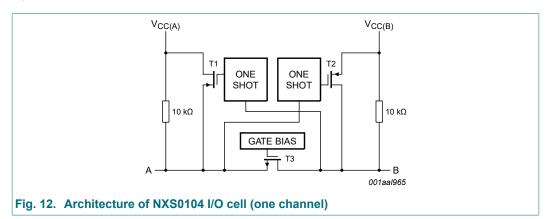
### 13.1. Applications

Voltage level-translation applications. The NXS0104 can be used in point-to-point applications to interface between devices or systems operating at different supply voltages. The device is primarily targeted at  $I^2C$  or 1-wire which use open-drain drivers, it may also be used in applications where push-pull drivers are connected to the ports, however the NXB0104 may be more suitable.



### 13.2. Architecture

The architecture of the NXS0104 is shown in <u>Fig. 12</u>. The device does not require an extra input signal to control the direction of data flow from A to B or B to A.



The NXS0104 is a "switch" type voltage translator, it employs two key circuits to enable voltage translation:

- 1. A pass-gate transistor (N-channel) that ties the ports together.
- 2. An output edge-rate accelerator that detects and accelerates rising edges on the I/O pins.

The gate bias voltage of the pass gate transistor (T3) is set at approximately one threshold voltage above the V<sub>CC</sub> level of the low-voltage side. During a LOW-to-HIGH transition the output one-shot accelerates the output transition by switching on the PMOS transistors (T1, T2) bypassing the 10 kΩ pull-up resistors and increasing current drive capability. The one-shot is activated once the input transition reaches approximately  $0.5V_{CCI}$ ; it is de-activated approximately 50 ns after the output reaches  $0.5V_{CCO}$ . During the acceleration time the driver output resistance is between approximately 50 Ω and 70 Ω.

To avoid signal contention and minimize dynamic  $I_{CC}$ , the user should wait for the one-shot circuit to turn-off before applying a signal in the opposite direction. Pull-up resistors are included in the device for DC current sourcing capability.

#### 13.3. Input driver requirements

As the NXS0104 is a switch type translator, properties of the input driver directly effect the output signal. The external open-drain or push-pull driver applied to an I/O determines the static current sinking capability of the system; the max data rate, HIGH-to-LOW output transition time ( $t_{THL}$ ) and propagation delay ( $t_{PHL}$ ) are dependent upon the output impedance and edge-rate of the external driver. The limits provided for these parameters in the datasheet assume a driver with output impedance below 50  $\Omega$  is used.

#### 13.4. Output load considerations

The maximum lumped capacitive load that can be driven is dependant upon the one-shot pulse duration. In cases with very heavy capacitive loading there is a risk that the output will not reach the positive rail within the one-shot pulse duration. To avoid excessive capacitive loading and to ensure correct triggering of the one-shot it's recommended to use short trace lengths and low capacitance connectors on NXS0104 PCB layouts. To ensure low impedance termination and avoid output signal oscillations and one-shot re-triggering, the length of the PCB trace should be such that the round trip delay of any reflection is within the one-shot pulse duration.

#### 13.5. Power up

During operation  $V_{CC(A)}$  must never be higher than  $V_{CC(B)}$ , however during power-up  $V_{CC(A)} \ge V_{CC(B)}$  does not damage the device, so any power supply can be ramped up first. There is no special power-up sequencing required. The NXS0104 includes circuitry that disables all output ports when either  $V_{CC(A)}$  or  $V_{CC(B)}$  is switched off.

#### 13.6. Enable and disable

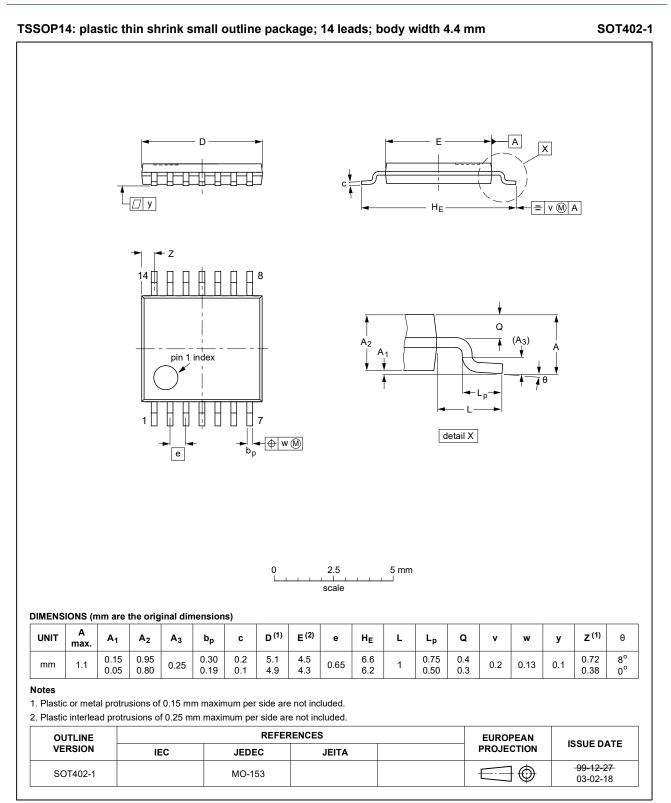
An output enable input (OE) is used to disable the device. Setting OE to LOW causes all I/Os to assume the high-impedance OFF-state. The disable time ( $t_{dis}$  with no external load) indicates the delay between when OE goes LOW and when outputs actually become disabled. The enable time ( $t_{en}$ ) indicates the amount of time the user must allow for one one-shot circuitry to become operational after OE is taken HIGH. To ensure the high-impedance OFF-state during power-up or power-down, pin OE should be tied to GND through a pull-down resistor, the minimum value of the resistor is determined by the current-sourcing capability of the driver.

#### 13.7. Pull-up or pull-down resistors on I/O lines

Each A port I/O has an internal 10 k $\Omega$  pull-up resistor to V<sub>CC(A)</sub>, and each B port I/O has an internal 10 k $\Omega$  pull-up resistor to V<sub>CC(B)</sub>. If a smaller value of pull-up resistor is required, an external resistor must be added parallel to the internal 10 k $\Omega$ , this will effect the V<sub>OL</sub> level. When OE goes LOW the internal pull-ups of the NXS0104 are disabled.

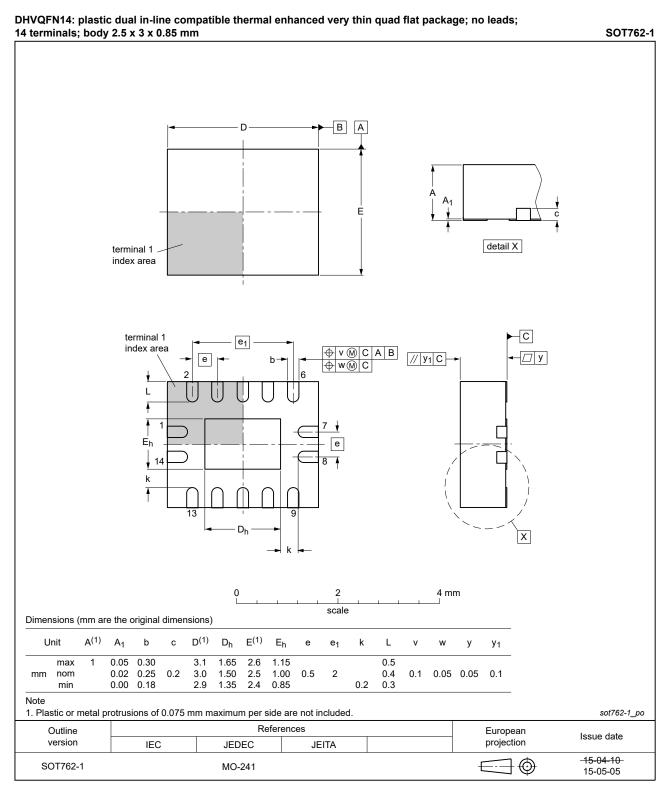
#### Dual supply translating transceiver; open drain; auto direction sensing

## 14. Package outline



#### Fig. 13. Package outline SOT402-1 (TSSOP14)

#### Dual supply translating transceiver; open drain; auto direction sensing





### Dual supply translating transceiver; open drain; auto direction sensing

XQFN12: plastic, extremely thin quad flat package; no leads; 12 terminals; body 1.70 x 2.00 x 0.50 mm

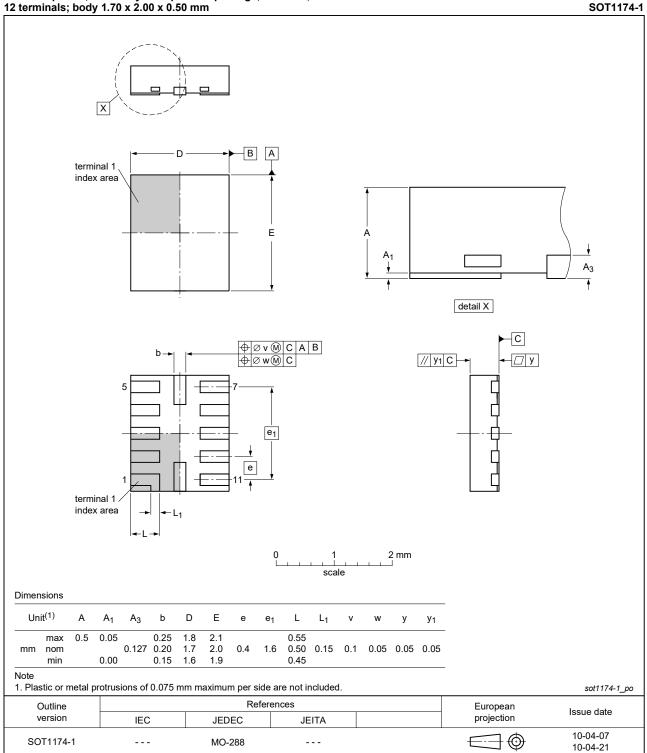
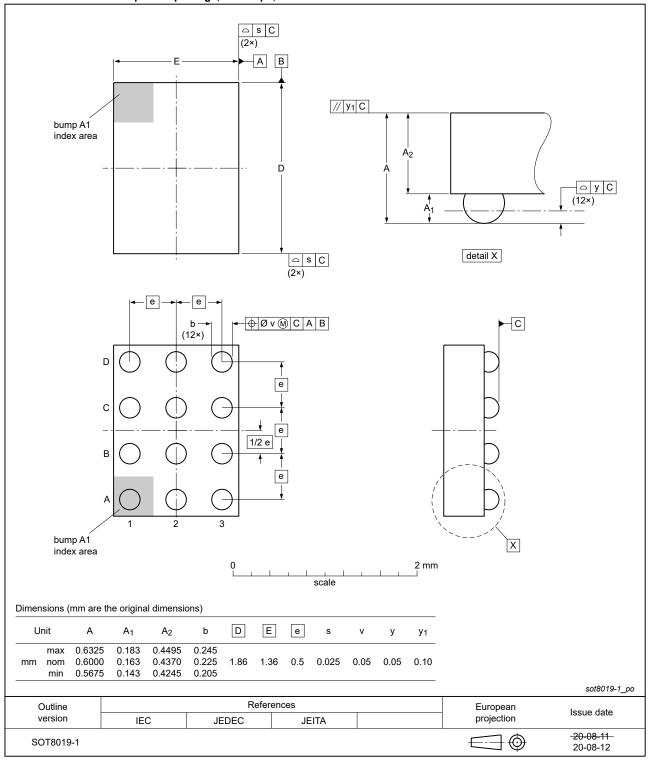


Fig. 15. Package outline SOT1174-1 (XQFN12)

### Dual supply translating transceiver; open drain; auto direction sensing

WLCSP12: wafer level chip-scale package, 12 bumps; 1.36 x 1.86 x 0.60 mm







## **15. Abbreviations**

Table 15. Abbreviations						
Acronym	Description					
CDM	Charged Device Model					
DUT	Device Under Test					
ESD	ElectroStatic Discharge					
HBM	Human Body Model					
l <sup>2</sup> C	Inter-Integrated Circuit					
PCB	Printed Circuit Board					
PRR	Pulse Rate Repetition					

### 16. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes			
NXS0104 v.4	20210630	Product data sheet	-	NXS0104 v.3			
Modifications:	Type numb	er NXS0104UM (SOT8019	)-1 / WLCSP12) ad	lded.			
NXS0104 v.3	20201113	Product data sheet	-	NXS0104 v.2			
Modifications:	• <u>Table 11</u> ar	nd <u>Table 12</u> : Disable times	updated				
NXS0104 v.2	20200827	Product data sheet	-	NXS0104 v.1			
Modifications:							
NXS0104 v.1	20190228	Product data sheet	-	-			

## 17. Legal information

#### **Data sheet status**

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

 Please consult the most recently issued document before initiating or completing a design.

- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at

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